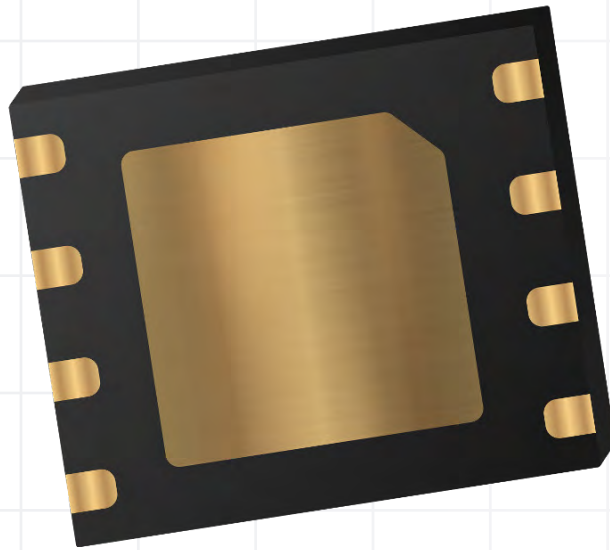


Global G1 eUICC SIM

Embedded SIM (eSIM) Format



Global G1 eUICC SIM

Embedded SIM Format - MFF2, DFN8

Product overview

A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs are eUICC compliant and the Hyper platform remotely updates coverage over-the-air by adding or removing profiles, without requiring you to swap the SIM in your device.

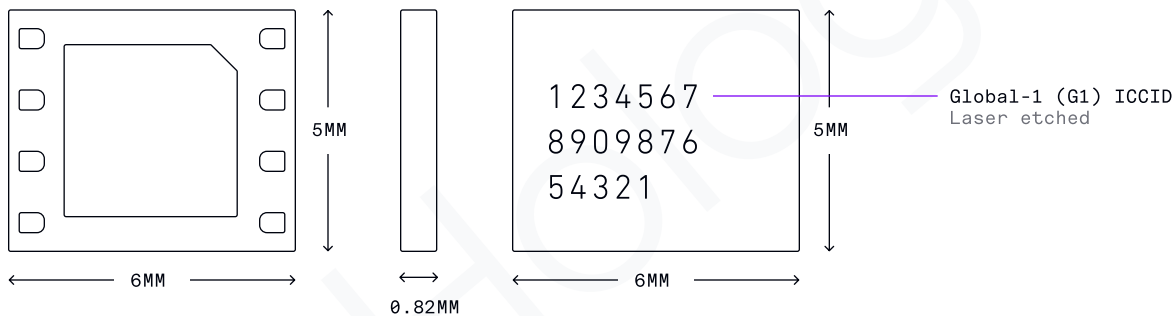
Network availability

Works globally with Hologram's 2G through 4G (LTE) network including LTE-M and NB-IoT where coverage is available. More information:

<https://www.hologram.io/pricing/coverage>

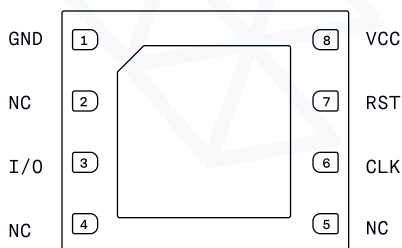
Mechanical specifications

Bottom view



Physical characteristics

Top view



Size

MFF2 (DFN8)	Embedded SIM	6 × 5 × 0.82 mm
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Part numbers

G1-DFN8

Past part numbers

GL1-MMF2, SIM-E-MFF2-GL

Multipack labeling

Single SIM: G1-DFN8
 250-pack: G1-DFN8-250
 2500-pack: G1-DFN8-2500

Pin definitions

Pin	Signal	Description
1	GND	Ground
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

Hardware features

Chip type

Supplier	Samsung
Chip Code	S3FW9FG

Electrical

Operating Voltage	1.6V, 3V, and 5V
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Hardware characteristics

Grade	Standard
Operational Temperature	-25°C to +85°C
Data Retention	25 years @ 25°C
Write Endurance	>500K read/write cycles @ 25°C (OS enhanced)
Memory (NVM)	340 KB
Memory (SRAM)	10 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 Class A, B, C – UICC Terminal Interface Physical & Logical Characteristics
 ETSI TS 102 671 v9.1.0 – M2M Physical and Logical Characteristics
 ISO/IEC 7816-3 standard for Cards with Contacts – Electrical interface and transmission protocols

Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS		SGP.11 RSP v3.1; SGP.14 eUICC PKI v1.1; SGP.02 v3.2 ; SGP.05 eUICC PP-0089
		eUICC Profile Package Interoperable Format Technical Specification v2.1
		Card Specification Version 2.1.1
Software		Java Card 3 Platform, Classic Edition version 3.0.4
		Release 8
Remote SIM provisioning		SGP.01 RSP v1.1 ; SGP.11 RSP v3.1 & 3.2; SGP.14 eUICC PKI v1.1 ; SAS-SM
Supplier's Declaration of Conformity	Manufactured according to the following standards: <ul style="list-style-type: none"> • RoHS Directive 2011/65/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 18001 • ISO 17025 	